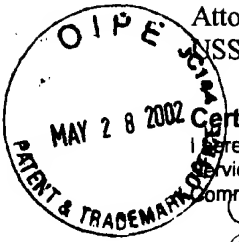


PATENT

Attorney Docket No.: CPAC 1003-1 US
NSSN 09/802,664

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner of Patents, Washington, D.C., 20231, on May 10, 2002.

Linda Shaw

Date _____

May 10, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of Rajendra D. Pendse

Application No.: 09/802,664

Filed: March 9, 2001

Title: Flip chip interconnection structure

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)
) Examiner: Unknown
)
) Group Art Unit: 2811
)
) Date: May 10, 2002

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SEPARATE LETTER TO OFFICIAL DRAFTSPERSON

Official Draftsperson
Commissioner Of Patents
Washington, D.C. 20231

Official Draftsperson:

In connection with the above-referenced U. S. patent application, transmitted herewith are the following papers:

- [X] Three (3) sheets of formal drawing(s) (Figs 1A, 1B, 2A, 2B, 3A, 3B, 4A, 4B, 5 and 6).

Authorization is hereby given to deduct from or credit to Deposit Account No. 50-0869 (CPAC 1003-1 US), any additional fees that may be required with this matter. A duplicate copy of this paper is enclosed.

Respectfully submitted,

Bill Kennedy

Registration No. 33,407

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Eq. No. 33,407